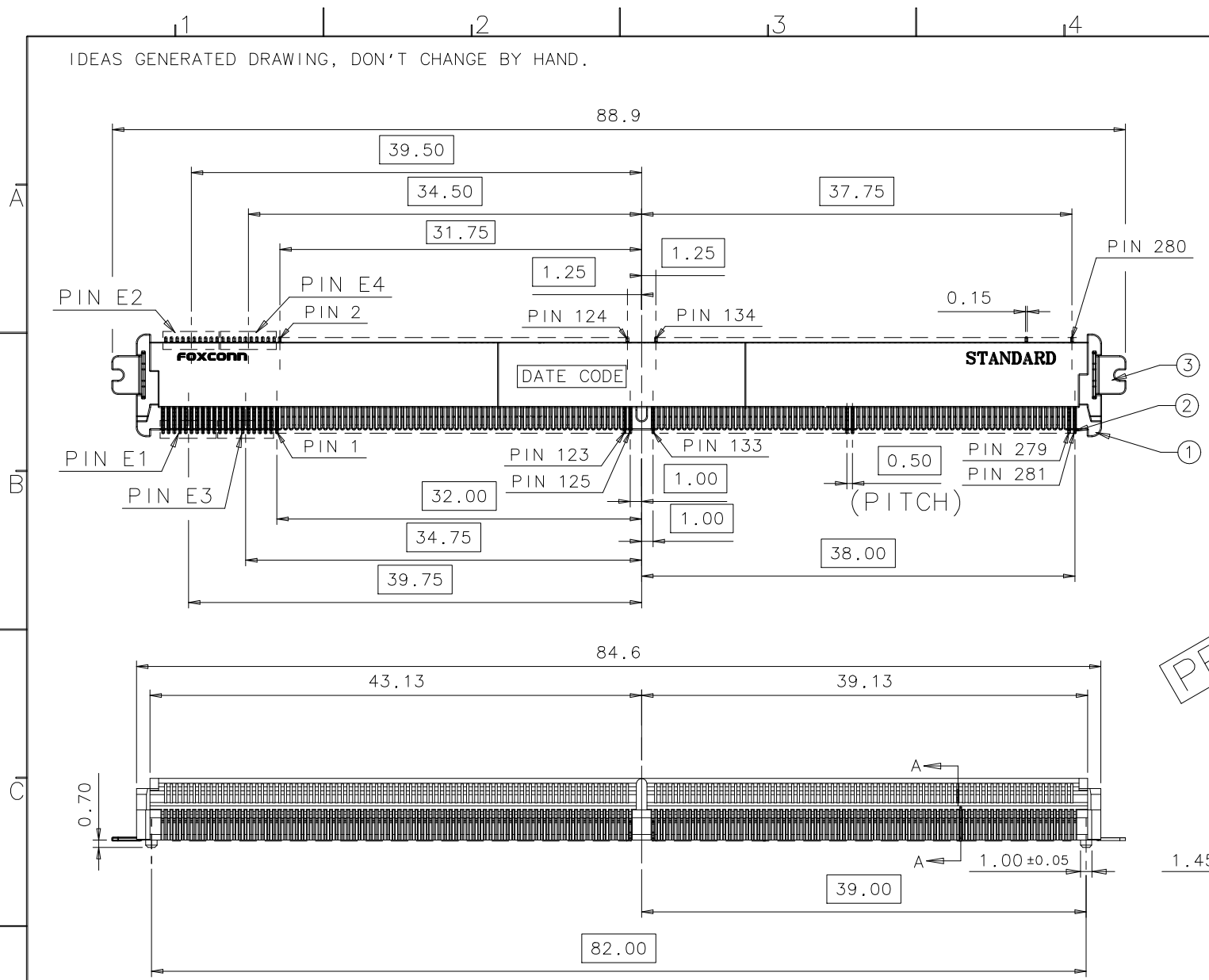


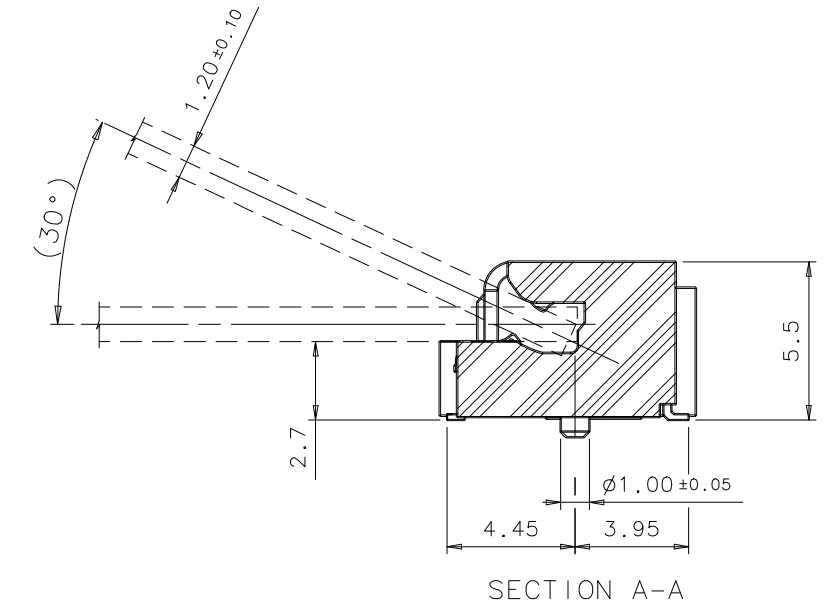
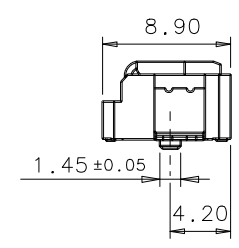
IDEAS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.
X1	PDK910098	Herry Yang
X2	PDK910229	Herry Yang

- NOTES:
- ELECTRICAL CHARACTERISTICS :
    - VOLTAGE RATING 50V DC PER CONTACT.
    - INSULATION RESISTANCE : 250MEGAOHMS. MIN. AT 500V DC.
  - MECHANICAL CHARACTERISTICS :
    - DURABILITY : 50 MATING CYCLES.
  - OPERATION TEMPERATURE : -40°C TO + 85°C
  - THE NVIDIA'S MOBILE PCI EXPRESS MODULE ELECTROMECHANICAL SPECIFICATION CONTROLS MXM GRAPHICS MODULE PCB AND CONNECTOR MOTHERBOARD FOOTPRINT DIMENSIONS. IT IS SHOWN FOR REFERENCE ONLY, AND IS SUBJECT TO CHANGE.
  - INTERPRET DRAWING PER ASME Y14.5M-1994.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



PROPOSAL



PART NO. DESCRIPTION: A S 0 B 8 2 \* - S 5 5 B - 7 H

MEMORY MODULE SOCKET — A  
 HORIZONTAL TYPE — S  
 SINGLE ROW — 0  
 NO. OF POS. — B8  
 B8= 314 POS. — 2  
 SMT — \*  
 CONTACT AREA PLATING — S  
 1=GOLD FLASH — 5  
 6=10u" GOLD PLATING — 5  
 H=HALOGEN/LEAD FREE — H  
 7=TAPE & REEL — 7  
 B=BLACK COLOR — B  
 55=5.5mm HEIGHT — 55  
 STANDARD — 7

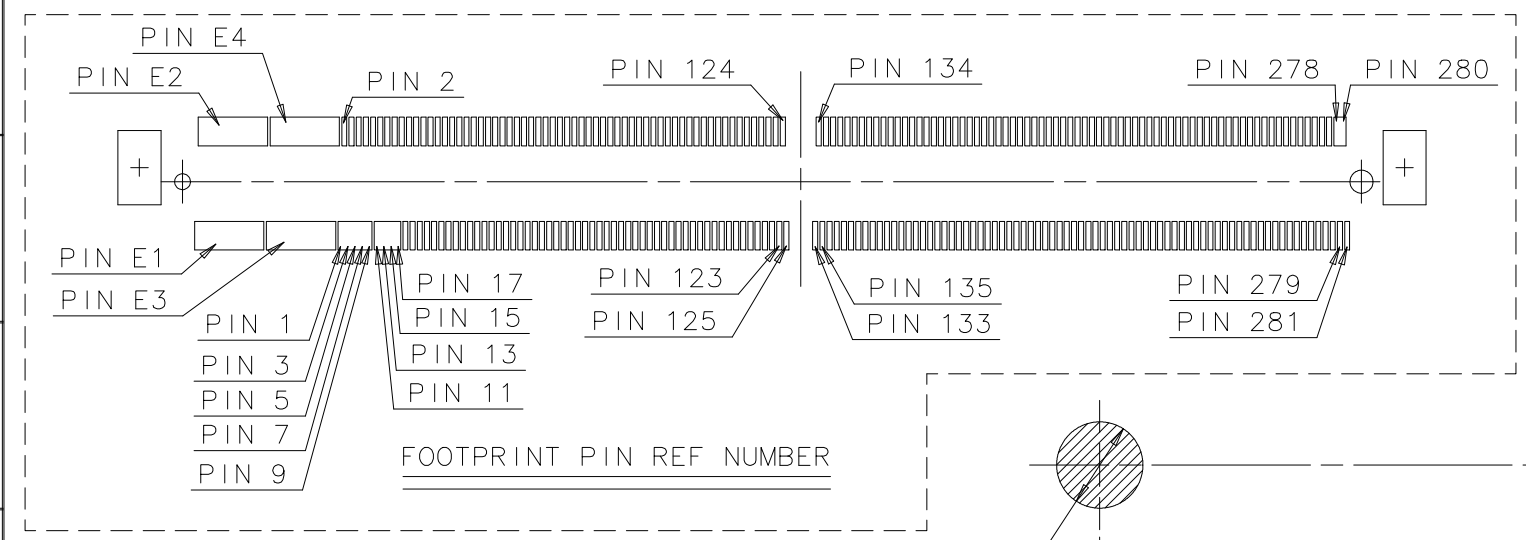
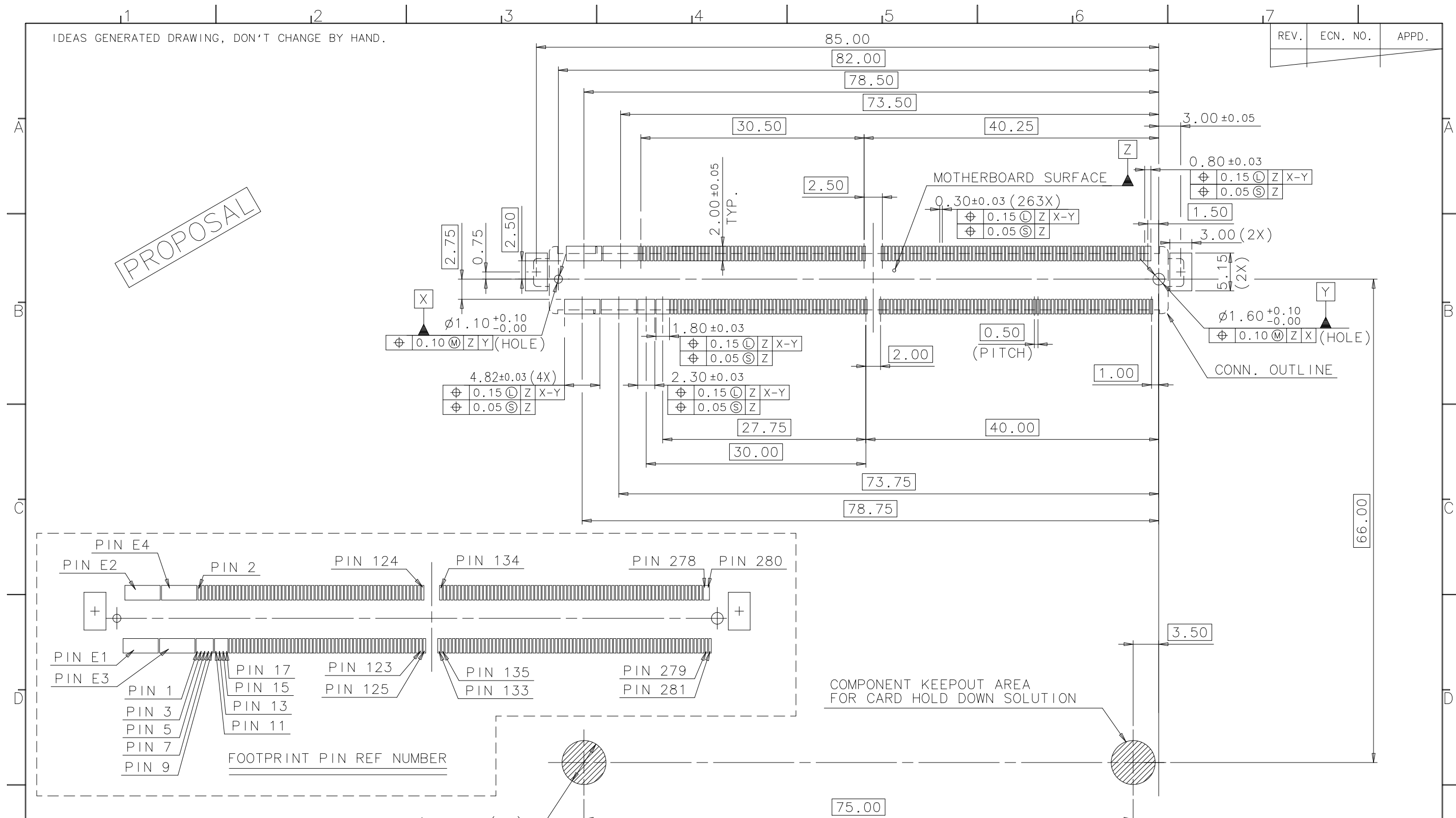
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
③	METAL EAR	2	COPPER ALLOY	PURE TIN PLATING OVER ALL
②	CONTACT	314	COPPER ALLOY	NICKEL UNDER PLATING GOLD FLASH PLATING AT TAIL AREA GOLD PLATING(OR GOLD FLASH) AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN FREE

X. ± 0.30	X°. ± 2.0°	UNITS	mm	NAME (INTENDED USE) MXM3.0 CONNECTOR 0.5P 314POS.	<b>FOXCONN</b> HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.
.X ± 0.20	.X° ± 1.0°	MAT'L			
.XX ± 0.15	.XX°	FINISH		PART NO. (INTENDED USE) ASOB82*-S55B-7H	TITLE: CUSTOMER DRAWING
.XXX±	.XXX°±		Q'TY		APPD: Herry Yang
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.				CHKD: Alex Wong	
				DR: F.L LIU 1/13'09	

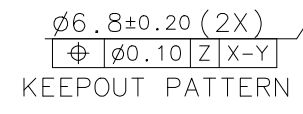
IDEAS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

PROPOSAL



COMPONENT KEEPOUT AREA FOR CARD HOLD DOWN SOLUTION



RECOMMENDED PCB LAYOUT

X. ±	X°. ±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN</b> HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.
.X ± 0.10	.X°. ±	MAT'L		MXM3.0 CONNECTOR 0.5P 314POS.	
.XX ± 0.05	.XX°. ±	FINISH		PART NO. (INTENDED USE)	TITLE:
.XXX ±	.XXX°. ±	Q'TY		AS0B82*-S55B-7H	CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.				APPD:	DWG NO.:
				Herry Yang	317-0000-1743
				CHKD:	SCALE SHEET REV.
Alex Wong	N/A 2/2 X2	DR:	F.L LIU 1/13'09		